Amendments to the Specification

Please replace paragraph [0009] with the following amended paragraph:

[0009] Fig. 2 illustrates the gas micro-bubble and particulate defect concerns associated with the water immersion lens fluid and its material interfaces. Fig. 2 is a cross-sectional diagram 200 showing close views of the water immersion lens 106 and the fluid's interfaces to the contacted wafer's photoresist layer 104 and to the contacted objective lens 108 of the immersion lithography system. The fluid of the water immersion lens 106 is in direct contact to the lowest surface of the objective lens 108 at the interface labeled 208 on the diagram. The fluid of the water immersion lens 106 is in direct contact to the top surface of the photoresist (or photoresist protective) layer 104 at the interface labeled 210 on the diagram. The water immersion fluid flow is depicted by the two horizontal arrows drawn pointing towards the left. The right most arrow pointing left indicates the flow of water immersion lens fluid into the immersion lens 106. The left most arrow pointing left indicates the flow of fluid out of the water immersion lens ~~202~~ 106. It shows three defect types located within the water immersion lens ~~202~~ 106. There are resist defects (R), micro-bubbles (B) and general, miscellaneous particulates (P). Some of the described defects, R, B and P, are free, floating within the water immersion lens ~~202~~ 106. Other defects, R, B and P are shown adhering to the two immersion lens interfaces, 208 and 210. It is noted that many of the adhered defects may have strong enough adhering forces that may not be overcome and released by the applied forces of the incoming flow of fluid. As a result, such defects may continue to grow and build, to become large enough to distort and disturb the quality of the printed pattern upon the photoresist.